

ABSTRACT

A metal contact for a copper alloy surface, comprising: electroplated barrier layer having a thickness ranging from about 0.00001 inch to about 0.0001 inch, wherein the barrier layer is selected from the group consisting of cobalt, cobalt-nickel alloys, cobalt-tungsten alloys, cobalt-nickel-tungsten alloys, and rhodium.

1 C 0 4 E 0 E 0 C 0 4 A 2 3 4 C 0